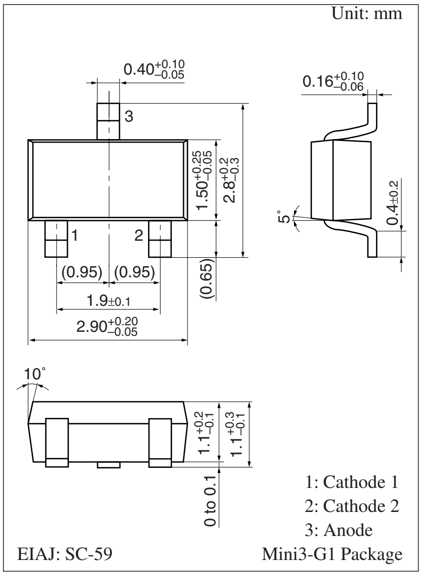
MAZC062D

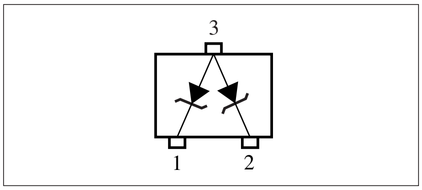
Silicon planar type

For surge absorption circuit



Marking Symbol: 6.2C

Internal Connection



■ Features

- Low joint capacity zener diode
- Two elements anode-common type

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Power dissipation*	P_D	200	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

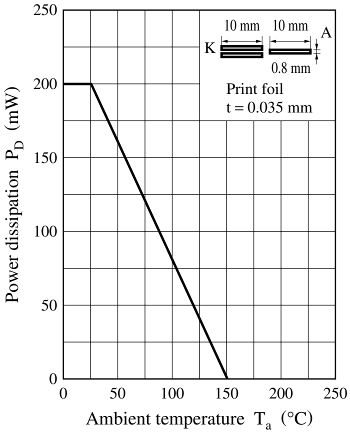
Note) ∗: P_{tot} = 200 mW achieved with a printed circuit board.

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

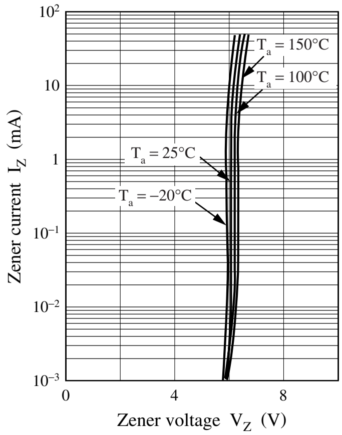
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 10 mA		0.9	1.0	V
Zener voltage*	V_Z	I_Z = 5 mA	5.9		6.5	V
Zener rise operating resistance	R_{ZK}	I_Z = 0.5 mA			100	Ω
Zener operating resistance	R_Z	I_Z = 5 mA		30	Ω	
Reverse current	I_R	V_R = 5.5 V			3	µA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		8		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 5 MHz
3. Electrostatic breakdown voltage: ±15 kV
Test method: IEC-801 (C = 150 pF, R = 330 Ω, Contact discharge: 10 times)
Test unit: ESS-200AX
4. ∗: The V_Z value is for the temperature of 25°C. In other cases, carry out the temperature compensation.
Guaranteed at 20 ms after power application.

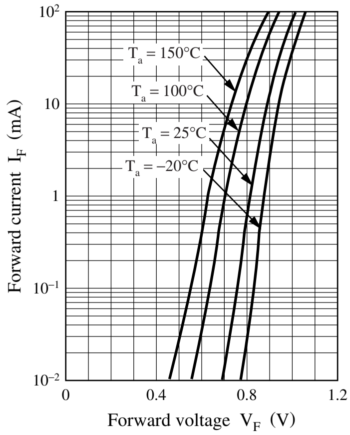
P_D — T_a



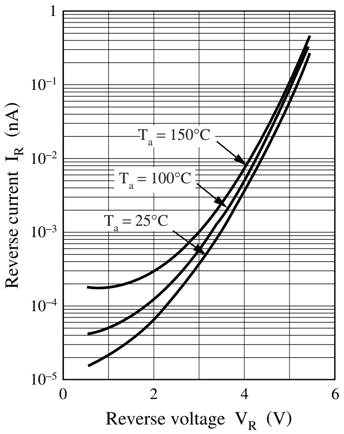
I_Z — V_Z



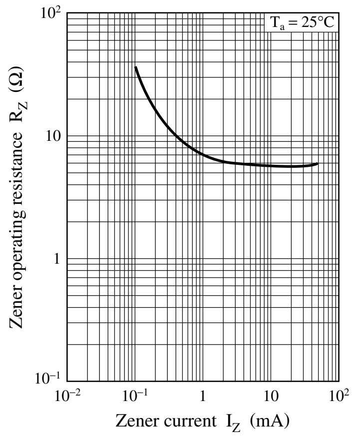
I_F — V_F



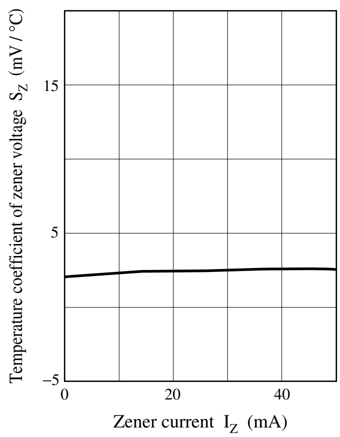
I_R — V_R



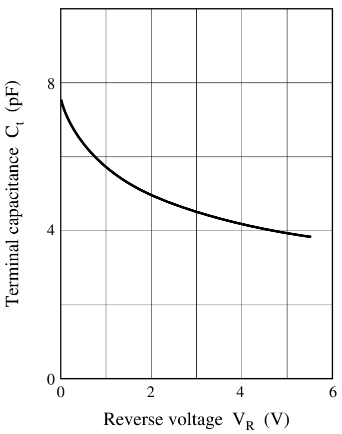
R_Z — I_Z



S_Z — I_Z



C_t — V_R



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